



## Final Product Change Notification

201903007F01

**Issue Date:** 30-Mar-2019

**Effective Date:** 28-Jun-2019

Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)

**This notice is NXP Company Proprietary.**



### Management Summary

BE2 transferring from ASEK to ATKH (grinding/sawing/marketing and packing).

BE2 (back half of the Assembly process) will be enabled in ATKH.

### Change Category

- |  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process  | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials  | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input type="checkbox"/> Assembly Location   | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware            | <input checked="" type="checkbox"/> Other - BE2 process transferring (Grinding/Sawing/Marking/Packing) |  |   |   |

ASEK Grinding/Sawing  
Transferring to ATKH -  
PCA9412AUK

### Description of Change

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH BE2.

The flow allows for manufacturing flexibility and helps ensure customer supply.

BE2(back half of the Assembly process) (grinding/sawing/marketing and packing) will be enabled in ATKH.

There's no change in Form, Fit or Function.

### Reason for Change

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH BE2.

The flow allows for manufacturing flexibility and helps ensure customer supply.

### Identification of Affected Products

Product identification does not change

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH BE2.

The flow allows for manufacturing flexibility and helps ensure customer supply.

## Product Availability

### Sample Information

Samples are available upon request

### Production

Planned first shipment 30-Apr-2019

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Additional information

Affected products and sales history information: see attached file

Self qualification: [view online](#)

Additional documents: [view online](#)



## Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 29-Apr-2019.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** Wenfeng Zhao

**Position** BL SIP Quality

**e-mail address** [wenfeng.zhao@nxp.com](mailto:wenfeng.zhao@nxp.com)

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

## About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors  
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.